



Material Content Data Sheet



Sales Product Name				BGSX 33MU16 E6327		Issued		12. February 2019	
MA#				MA004407966					
Package				PG-ULGA-16-3		Weight*		5.35 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.917	17.14	17.14	171379	171379	
bumps	non noble metal	copper	7440-50-8	0.028	0.52	0.52	5229	5229	
encapsulation	organic material	carbon black	1333-86-4	0.012	0.22		2243		
	plastics	epoxy resin	-	0.348	6.51		65057		
leadfinish	inorganic material	silicondioxide	60676-86-0	2.040	38.14	44.87	381368	448668	
	noble metal	palladium	7440-05-3	0.000	0.01		55		
	noble metal	gold	7440-57-5	0.000	0.01		88		
	non noble metal	nickel	7440-02-0	0.009	0.16	0.18	1603	1746	
substrate	inorganic material	aluminiumhydroxide	21645-51-2	0.283	5.30		52997		
	plastics	epoxy bismaleimide triazine resin	-	0.325	6.08		60849		
	inorganic material	glass fibre	-	0.441	8.24		82440		
solder	non noble metal	copper	7440-50-8	0.801	14.98	34.60	149768	346054	
	noble metal	silver	7440-22-4	0.000	0.01		51		
	non noble metal	tin	7440-31-5	0.015	0.28	0.29	2794	2845	
ubm	non noble metal	tungsten	7440-33-7	0.000	0.00		4		
	non noble metal	titanium	7440-32-6	0.000	0.00		7		
solder resists	non noble metal	copper	7440-50-8	0.000	0.00	0.00	20	31	
	inorganic material	silicondioxide	60676-86-0	0.014	0.26		2645		
	plastics	epoxy resin	-	0.017	0.31		3126		
	inorganic material	bariumsulfate	7727-43-7	0.028	0.53		5291		
*deviation	plastics	acrylic resin	-	0.069	1.30	2.40	12986	24048	
						Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com